



Dear Valued Customer,

The current mechanical specifications for the package can be found at the www.national.com web site or by clicking the following link:

<http://www.national.com/packaging/folders/sdb06a.html>

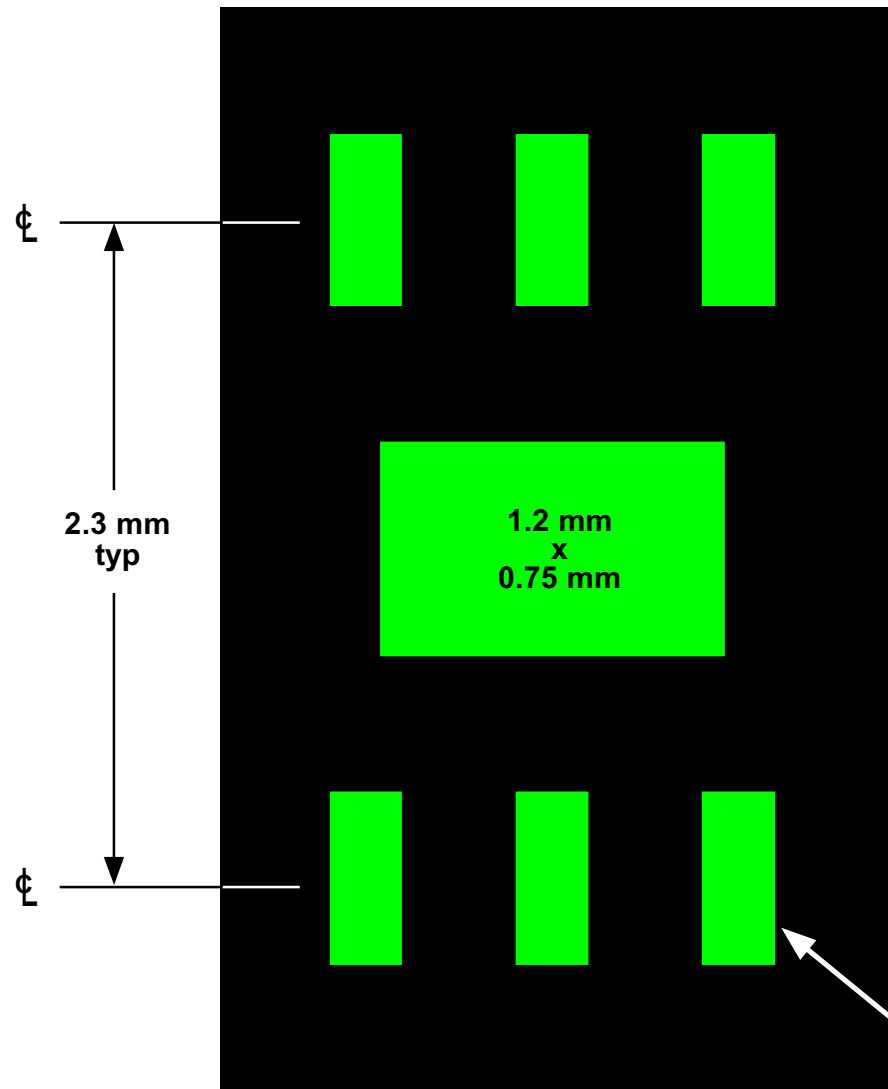
The following pages illustrate the recommended package footprints that apply to this package configuration. They are included in GERBER format for easy incorporation into most PCB layout packages.

For technical support, contact:

<http://www.national.com/support/>

Sincerely yours,

National Semiconductor

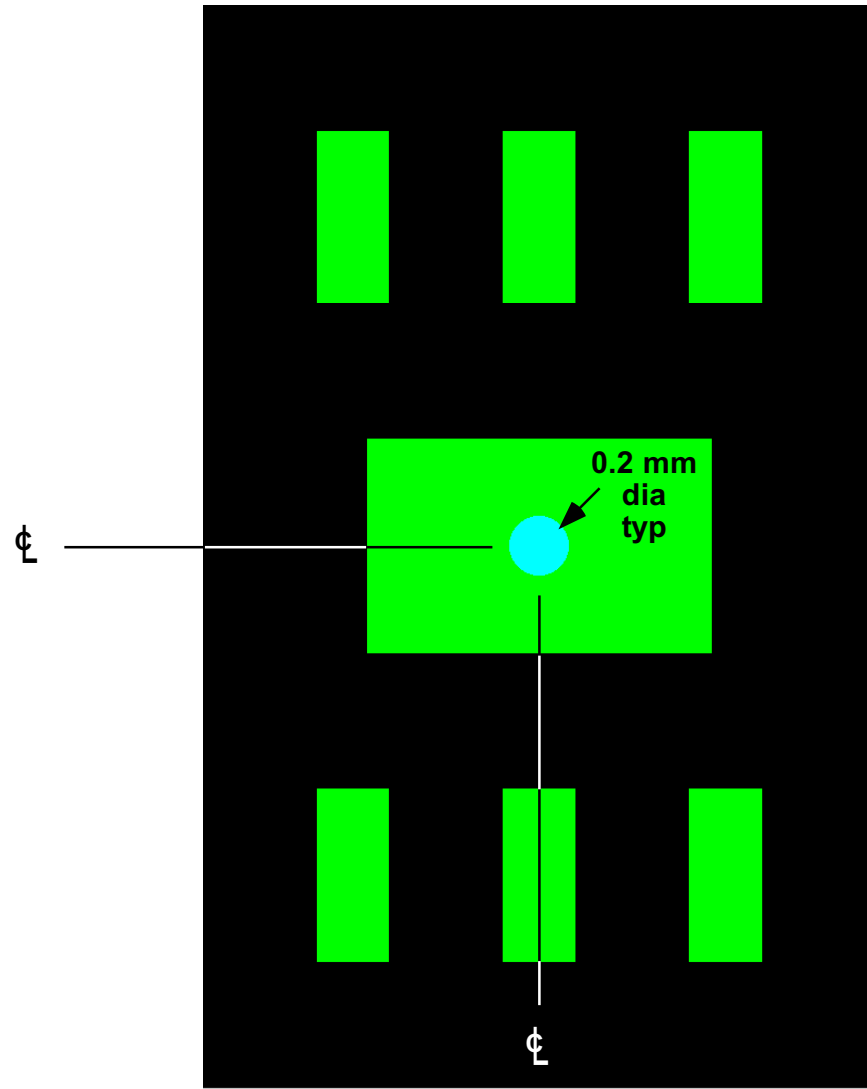


TOP ETCH

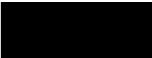
0.25 x 0.6 mm
Typ 6 places

 = Exposed FR4  = Exposed metal


NOTE:
Refer to package mechanical
drawing at the website for complete
mechanical dimensions.

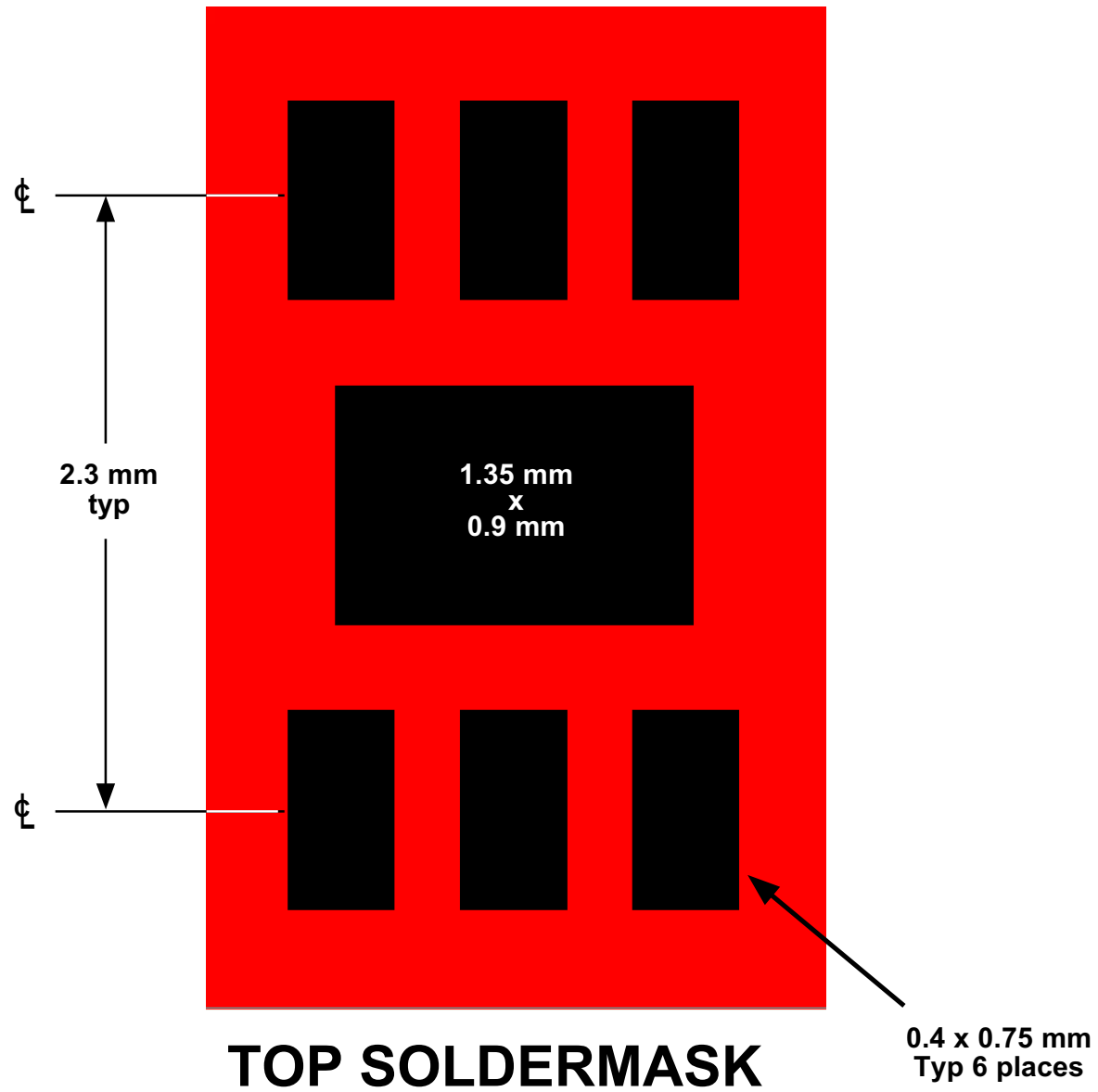


TOP ETCH with THERMAL VIA

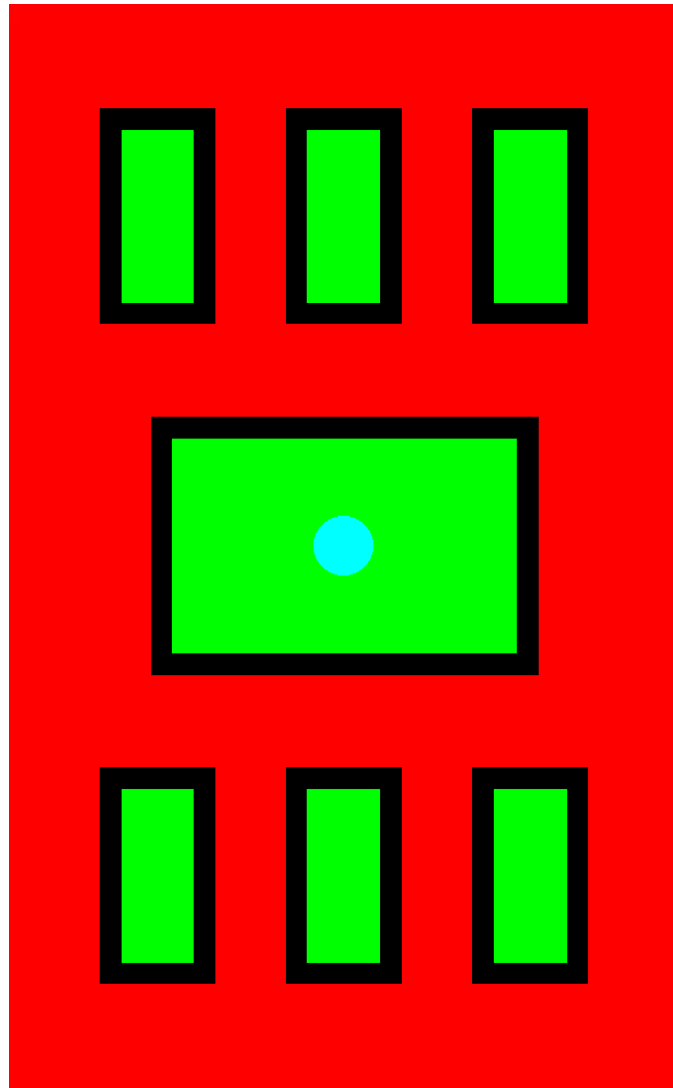
 = Exposed FR4

 = Exposed metal


 = Thermal Vias




-  = Exposed FR4
-  = Mask over FR4



TOP ETCH + SOLDERMASK + VIA

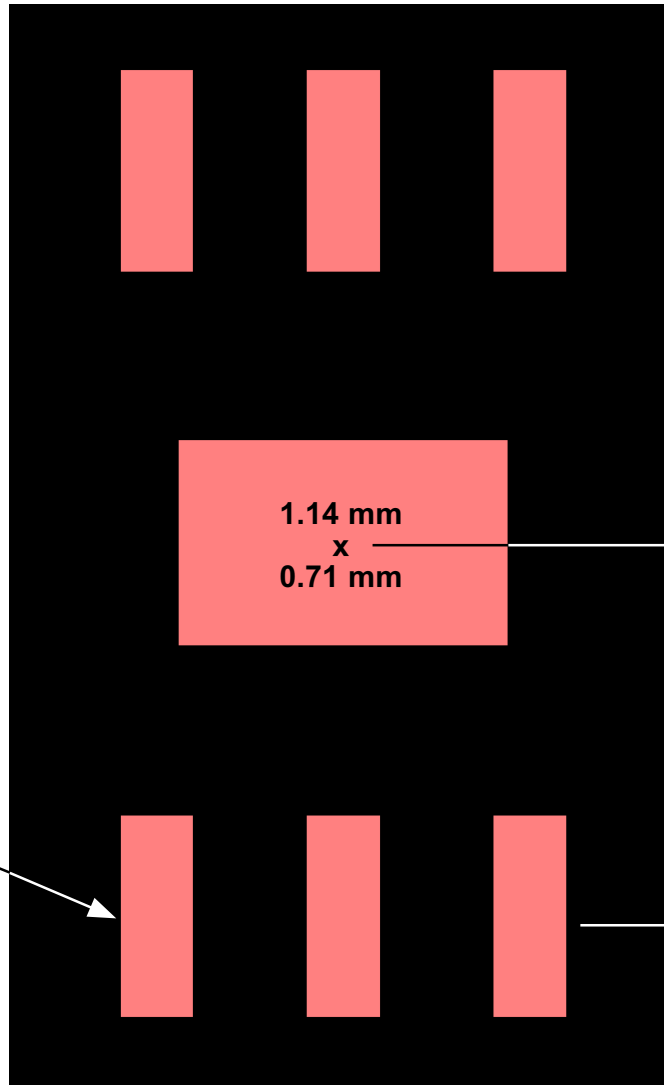
 = Exposed FR4

 = Exposed metal

 = Thermal Vias

 = Mask over FR4


0.25
x
0.7 mm
typ 6 places



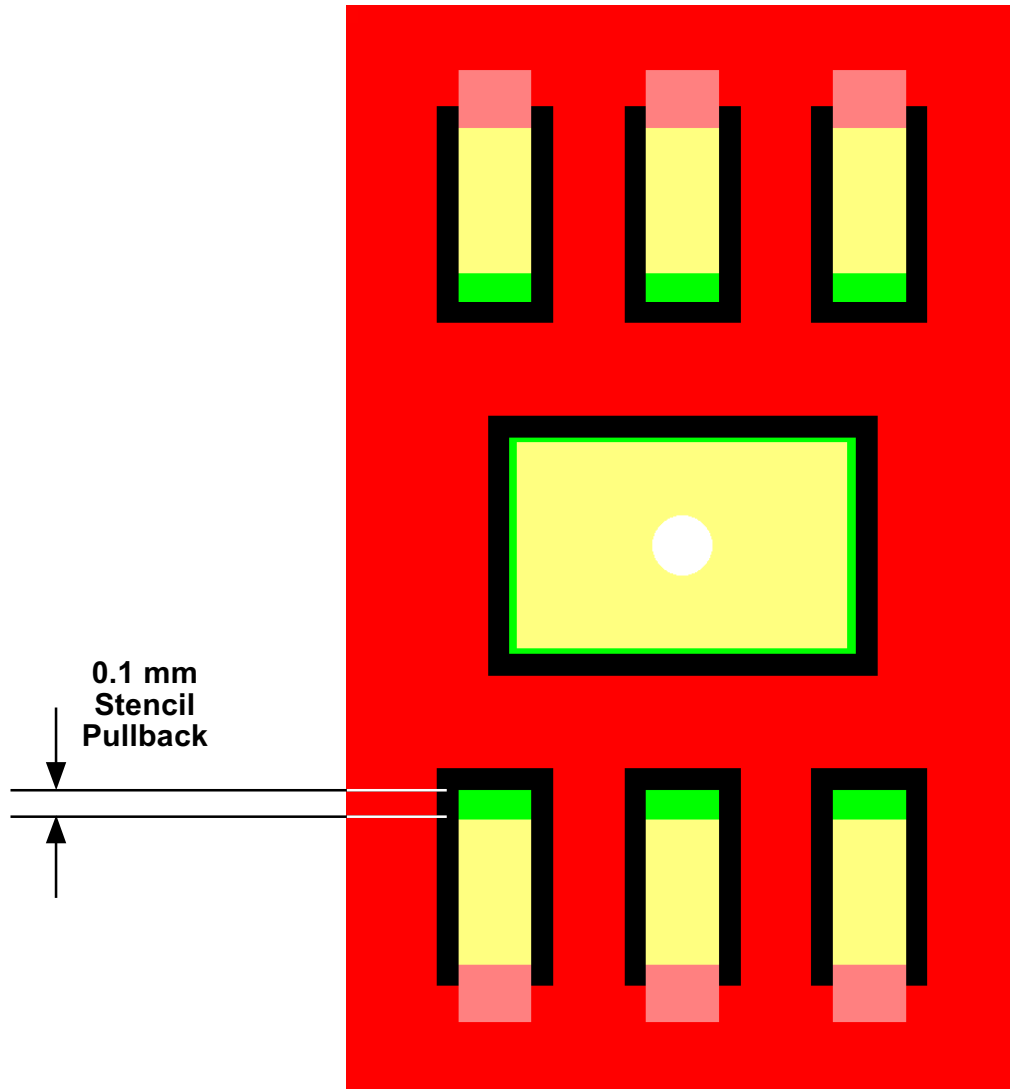
1.14 mm
x
0.71 mm

1.3 mm
typ

TOP SOLDERPASTE

 = Paste

Note:
Recommended stencil thickness is
of 0.127mm (0.005").



TOP ETCH + SOLDERMASK + SOLDERPASTE + VIA

- = Exposed FR4
- = Exposed metal
- = Paste over FR4 (0.2mm offset)
- = Mask over FR4
- = Paste over Metal
- = Thermal Vias under Paste